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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, LINbus, SCI, SPI
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	88
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	48K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 24x12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f51308adfp-30

Table 1.6 List of Pins and Pin Functions (80-Pin LFQFP) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TMR, POE)	Communications (SCIg, SCIh, RSPI, RIIC)	Touch sensing	Others
1		P06*1				
2		P03*1				DA0
3		P04*1				
4	VCL					
5		PJ1	MTIOC3A			
6	MD					FINED
7	XCIN					
8	XCOUT					
9	RES#					
10	XTAL	P37				
11	VSS					
12	EXTAL	P36				
13	VCC					
14		P35				NMI
15		P34	MTIOC0A/TMCI3/POE2#	SCK6		IRQ4
16		P32	MTIOC0C/TMO3	TXD6/SMOSI6/SSDA6	TS0	IRQ2/RTCOUT
17		P31	MTIOC4D/TMCI2	CTS1#/RTS1#/SS1#	TS1	IRQ1
18		P30	MTIOC4B/TMRI3/POE8#	RXD1/SMISO1/SSCL1	TS2	IRQ0
19		P27	MTIOC2B/TMCI3	SCK1	TS3	
20		P26	MTIOC2A/TMO1	TXD1/SMOSI1/SSDA1	TS4	
21		P21	MTIOC1B/TMCI0			
22		P20	MTIOC1A/TMRI0			
23	(5V tolerant)	P17	MTIOC3A/MTIOC3B/TMO1/ POE8#	SCK1/MISOA/SDA		IRQ7
24	(5V tolerant)	P16	MTIOC3C/MTIOC3D/TMO2	TXD1/SMOSI1/SSDA1/MOSIA/SCL		IRQ6/RTCOUT/ ADTRG0#
25		P15	MTIOC0B/MTCLKB/TMCI2	RXD1/SMISO1/SSCL1	TS5	IRQ5
26		P14	MTIOC3A/MTCLKA/TMRI2	CTS1#/RTS1#/SS1#	TS6	IRQ4
27	(5V tolerant)	P13	MTIOC0B/TMO3	SDA		IRQ3
28	(5V tolerant)	P12	TMCI1	SCL		IRQ2
29		PH3	TMCI0		TS7	
30		PH2	TMRI0		TS8	IRQ1
31		PH1	TMO0		TS9	IRQ0
32		PH0			TS10	CACREF
33		P55	MTIOC4D/TMO3		TS11	
34		P54	MTIOC4B/TMCI1		TS12	
35		PC7	MTIOC3A/TMO2/MTCLKB	MISOA	TS13	CACREF
36		PC6	MTIOC3C/MTCLKA/TMCI2	MOSIA	TS14	
37		PC5	MTIOC3B/MTCLKD/TMRI2	RSPCKA	TS15	
38		PC4	MTIOC3D/MTCLKC/TMCI1/ POE0#	SCK5/SSLA0	TSCAP	
39		PC3	MTIOC4D	TXD5/SMOSI5/SSDA5	TS16	
40		PC2	MTIOC4B	RXD5/SMISO5/SSCL5/SSLA3	TS17	
41		PB7/ PC1*2	MTIOC3B		TS18	
42		PB6/ PC0*2	MTIOC3D		TS19	
43		PB5	MTIOC2A/MTIOC1B/TMRI1/ POE1#		TS20	
44		PB4			TS21	
45		PB3	MTIOC0A/MTIOC4A/TMO0/ POE3#	SCK6	TS22	
46		PB2		CTS6#/RTS6#/SS6#	TS23	
47		PB1	MTIOC0C/MTIOC4C/TMCI0	TXD6/SMOSI6/SSDA6	TS24	IRQ4/CMPOB1
48	VCC					
49		PB0	MTIC5W	RXD6/SMISO6/SSCL6/RSPCKA	TS25	

Table 1.7 List of Pins and Pin Functions (64-Pin LFQFP/LQFP) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TMR, POE)	Communications (SCIg, SCIh, RSPI, RIIC)	Touch sensing	Others
1		P03*1				DA0
2	VCL					
3	MD					FINED
4	XCIN					
5	XCOUT					
6	RES#					
7	XTAL	P37				
8	VSS					
9	EXTAL	P36				
10	VCC					
11		P35				NMI
12		P32	MTIOC0C/TMO3	TXD6/SMOSI6/SSDA6	TS0	IRQ2/RTCOUT
13		P31	MTIOC4D/TMCI2	CTS1#/RTS1#/SS1#	TS1	IRQ1
14		P30	MTIOC4B/TMRI3/POE8#	RXD1/SMISO1/SSCL1	TS2	IRQ0
15		P27	MTIOC2B/TMCI3	SCK1	TS3	
16		P26	MTIOC2A/TMO1	TXD1/SMOSI1/SSDA1	TS4	
17	(5V tolerant)	P17	MTIOC3A/MTIOC3B/TMO1/ POE8#	SCK1/MISOA/SDA		IRQ7
18	(5V tolerant)	P16	MTIOC3C/MTIOC3D/TMO2	TXD1/SMOSI1/SSDA1/MOSIA/SCL		IRQ6/RTCOUT/ ADTRG0#
19		P15	MTIOC0B/MTCLKB/TMCI2	RXD1/SMISO1/SSCL1	TS5	IRQ5
20		P14	MTIOC3A/MTCLKA/TMRI2	CTS1#/RTS1#/SS1#	TS6	IRQ4
21		PH3	TMCI0		TS7	
22		PH2	TMRI0		TS8	IRQ1
23		PH1	TMO0		TS9	IRQ0
24		PH0			TS10	CACREF
25		P55	MTIOC4D/TMO3		TS11	
26		P54	MTIOC4B/TMCI1		TS12	
27		PC7	MTIOC3A/TMO2/MTCLKB	MISOA	TS13	CACREF
28		PC6	MTIOC3C/MTCLKA/TMCI2	MOSIA	TS14	
29		PC5	MTIOC3B/MTCLKD/TMRI2	RSPCKA	TS15	
30		PC4	MTIOC3D/MTCLKC/TMCI1/ POE0#	SCK5/SSLA0	TSCAP	
31		PC3	MTIOC4D	TXD5/SMOSI5/SSDA5	TS16	
32		PC2	MTIOC4B	RXD5/SMISO5/SSCL5/SSLA3	TS17	
33		PB7/ PC1*2	MTIOC3B		TS18	
34		PB6/ PC0*2	MTIOC3D		TS19	
35		PB5	MTIOC2A/MTIOC1B/TMRI1/ POE1#		TS20	
36		PB3	MTIOC0A/MTIOC4A/TMO0/ POE3#	SCK6	TS22	
37		PB1	MTIOC0C/MTIOC4C/TMCI0	TXD6/SMOSI6/SSDA6	TS24	IRQ4/CMPOB1
38	VCC					
39		PB0	MTIC5W	RXD6/SMISO6/SSCL6/RSPCKA	TS25	
40	VSS					
41		PA6	MTIC5V/MTCLKB/TMCI3/ POE2#	CTS5#/RTS5#/SS5#/MOSIA	TS26	
42		PA4	MTIC5U/MTCLKA/TMRI0	TXD5/SMOSI5/SSDA5/SSLA0	TS28	IRQ5/CVREFB1
43		PA3	MTIOC0D/MTCLKD	RXD5/SMISO5/SSCL5	TS29	IRQ6/CMPB1
44		PA1	MTIOC0B/MTCLKC	SCK5/SSLA2	TS31	
45		PA0	MTIOC4A	SSLA1	TS32	CACREF
46		PE5	MTIOC4C/MTIOC2B			IRQ5/AN021/CMPOB0
47		PE4	MTIOC4D/MTIOC1A		TS33	AN020/CMPA2/ CLKOUT
48		PE3	MTIOC4B/POE8#	CTS12#/RTS12#/SS12#	TS34	AN019/CLKOUT

Table 1.7 List of Pins and Pin Functions (64-Pin LFQFP/LQFP) (2/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TMR, POE)	Communications (SCIg, SCIh, RSPI, RIIC)	Touch sensing	Others
49		PE2	MTIOC4A	RXD12/RXDX12/SMISO12/SSCL12	TS35	IRQ7/AN018/CVREFB0
50		PE1	MTIOC4C	TXD12/TXDX12/SIOX12/SMOSI12/ SSDA12		AN017/CMPB0
51		PE0		SCK12		AN016
52		P47*1				AN007
53		P46*1				AN006
54		P45*1				AN005
55		P44*1				AN004
56		P43*1				AN003
57		P42*1				AN002
58		P41*1				AN001
59	VREFL0	PJ7*1				
60		P40*1				AN000
61	VREFH0	PJ6*1				
62	AVCC0					
63		P05*1				DA1
64	AVSS0					

Note 1. The power source of the I/O buffer for these pins is AVCC0.
Note 2. PC0 and PC1 are valid only when the port switching function is selected.

2.1 General-Purpose Registers (R0 to R15)

This CPU has 16 general-purpose registers (R0 to R15). R0 to R15 can be used as data registers or address registers. R0, a general-purpose register, also functions as the stack pointer (SP). The stack pointer is switched to operate as the interrupt stack pointer (ISP) or user stack pointer (USP) by the value of the stack pointer select bit (U) in the processor status word (PSW).

2.2 Control Registers

(1) Interrupt Stack Pointer (ISP)/User Stack Pointer (USP)

The stack pointer (SP) can be either of two types, the interrupt stack pointer (ISP) or the user stack pointer (USP). Whether the stack pointer operates as the ISP or USP depends on the value of the stack pointer select bit (U) in the processor status word (PSW).
Set the ISP or USP to a multiple of 4, as this reduces the numbers of cycles required to execute interrupt sequences and instructions entailing stack manipulation.

(2) Interrupt Table Register (INTB)

The interrupt table register (INTB) specifies the address where the relocatable vector table starts.

(3) Program Counter (PC)

The program counter (PC) indicates the address of the instruction being executed.

(4) Processor Status Word (PSW)

The processor status word (PSW) indicates the results of instruction execution or the state of the CPU.

(5) Backup PC (BPC)

The backup PC (BPC) is provided to speed up response to interrupts.
After a fast interrupt has been generated, the contents of the program counter (PC) are saved in the BPC register.

(6) Backup PSW (BPSW)

The backup PSW (BPSW) is provided to speed up response to interrupts.
After a fast interrupt has been generated, the contents of the processor status word (PSW) are saved in the BPSW. The allocation of bits in the BPSW corresponds to that in the PSW.

(7) Fast Interrupt Vector Register (FINTV)

The fast interrupt vector register (FINTV) is provided to speed up response to interrupts.
The FINTV register specifies a branch destination address when a fast interrupt has been generated.

2.3 Register Associated with DSP Instructions

(1) Accumulator (ACC)

The accumulator (ACC) is a 64-bit register used for DSP instructions. The accumulator is also used for the multiply and multiply-and-accumulate instructions; EMUL, EMULU, MUL, and RMPA, in which case the prior value in the accumulator is modified by execution of the instruction.
Use the MVTACHI and MVTACLO instructions for writing to the accumulator. The MVTACHI and MVTACLO instructions write data to the higher-order 32 bits (bits 63 to 32) and the lower-order 32 bits (bits 31 to 0), respectively.
Use the MVFACHI and MVFACMI instructions for reading data from the accumulator. The MVFACHI and MVFACMI instructions read data from the higher-order 32 bits (bits 63 to 32) and the middle 32 bits (bits 47 to 16), respectively.

3. Address Space

3.1 Address Space

This MCU has a 4-Gbyte address space, consisting of the range of addresses from 0000 0000h to FFFF FFFFh. That is, linear access to an address space of up to 4 Gbytes is possible, and this contains both program and data areas.
Figure 3.1 shows the memory maps.

4. I/O Registers

This section provides information on the on-chip I/O register addresses and bit configuration. The information is given as shown below. Notes on writing to registers are also given below.

(1) I/O register addresses (address order)

- Registers are listed from the lower allocation addresses.
- Registers are classified according to module symbols.
- Numbers of cycles for access indicate numbers of cycles of the given base clock.
- Among the internal I/O register area, addresses not listed in the list of registers are reserved. Reserved addresses must not be accessed. Do not access these addresses; otherwise, the operation when accessing these bits and subsequent operations cannot be guaranteed.

(2) Notes on writing to I/O registers

When writing to an I/O register, the CPU starts executing the subsequent instruction before completing I/O register write. This may cause the subsequent instruction to be executed before the post-update I/O register value is reflected on the operation.
As described in the following examples, special care is required for the cases in which the subsequent instruction must be executed after the post-update I/O register value is actually reflected.

[Examples of cases requiring special care]

- The subsequent instruction must be executed while an interrupt request is disabled with the IENj bit in IERn of the ICU (interrupt request enable bit) cleared to 0.
- A WAIT instruction is executed immediately after the preprocessing for causing a transition to the low power consumption state.

In the above cases, after writing to an I/O register, wait until the write operation is completed using the following procedure and then execute the subsequent instruction.

(a) Write to an I/O register.
(b) Read the value from the I/O register to a general register.
(c) Execute the operation using the value read.
(d) Execute the subsequent instruction.

[Instruction examples]

- Byte-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.B  #SFR_DATA, [R1]
CMP    [R1].UB, R1
;; Next process
```

- Word-size I/O registers

```
MOV.L  #SFR_ADDR, R1
MOV.W  #SFR_DATA, [R1]
CMP    [R1].W, R1
;; Next process
```

4.1 I/O Register Addresses (Address Order)

Table 4.1 List of I/O Registers (Address Order) (1 / 18)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles
0008 0000h	SYSTEM	Mode Monitor Register	MDMONR	16	16	3 ICLK
0008 0008h	SYSTEM	System Control Register 1	SYSCR1	16	16	3 ICLK
0008 000Ch	SYSTEM	Standby Control Register	SBYCR	16	16	3 ICLK
0008 0010h	SYSTEM	Module Stop Control Register A	MSTPCRA	32	32	3 ICLK
0008 0014h	SYSTEM	Module Stop Control Register B	MSTPCRB	32	32	3 ICLK
0008 0018h	SYSTEM	Module Stop Control Register C	MSTPCRC	32	32	3 ICLK
0008 001Ch	SYSTEM	Module Stop Control Register D	MSTPCRD	32	32	3 ICLK
0008 0020h	SYSTEM	System Clock Control Register	SCKCR	32	32	3 ICLK
0008 0026h	SYSTEM	System Clock Control Register 3	SCKCR3	16	16	3 ICLK
0008 0028h	SYSTEM	PLL Control Register	PLLCR	16	16	3 ICLK
0008 002Ah	SYSTEM	PLL Control Register 2	PLLCR2	8	8	3 ICLK
0008 0032h	SYSTEM	Main Clock Oscillator Control Register	MOSCCR	8	8	3 ICLK
0008 0033h	SYSTEM	Sub-Clock Oscillator Control Register	SOSCCR	8	8	3 ICLK
0008 0034h	SYSTEM	Low-Speed On-Chip Oscillator Control Register	LOCOCR	8	8	3 ICLK
0008 0035h	SYSTEM	IWDT-Dedicated On-Chip Oscillator Control Register	ILOCOCR	8	8	3 ICLK
0008 0036h	SYSTEM	High-Speed On-Chip Oscillator Control Register	HOCOCR	8	8	3 ICLK
0008 003Ch	SYSTEM	Oscillation Stabilization Flag Register	OSCOVFSR	8	8	3 ICLK
0008 003Dh	SYSTEM	High-Speed On-Chip Oscillator Forced Oscillation Control Register	HOFCR	8	8	3 ICLK
0008 003Eh	SYSTEM	CLKOUT Output Control Register	CKOCR	16	16	3 ICLK
0008 0040h	SYSTEM	Oscillation Stop Detection Control Register	OSTDCR	8	8	3 ICLK
0008 0041h	SYSTEM	Oscillation Stop Detection Status Register	OSTDSR	8	8	3 ICLK
0008 0060h	SYSTEM	Low-Speed On-Chip Oscillator Trimming Register	LOCOTRR	8	8	3 ICLK
0008 0064h	SYSTEM	IWDT-Dedicated On-Chip Oscillator Trimming Register	ILOCOTRR	8	8	3 ICLK
0008 0068h	SYSTEM	High-Speed On-Chip Oscillator Trimming Register 0	HOCOTRR0	8	8	3 ICLK
0008 00A0h	SYSTEM	Operating Power Control Register	OPCCR	8	8	3 ICLK
0008 00A1h	SYSTEM	Sleep Mode Return Clock Source Switching Register	RSTCKCR	8	8	3 ICLK
0008 00A2h	SYSTEM	Main Clock Oscillator Wait Control Register	MOSCWTCR	8	8	3 ICLK
0008 00AAh	SYSTEM	Sub Operating Power Control Register	SOPCCR	8	8	3 ICLK
0008 00B0h	LPT	Low-Power Timer Control Register 1	LPTCR1	8	8	3 ICLK
0008 00B1h	LPT	Low-Power Timer Control Register 2	LPTCR2	8	8	3 ICLK
0008 00B2h	LPT	Low-Power Timer Control Register 3	LPTCR3	8	8	3 ICLK
0008 00B4h	LPT	Low-Power Timer Cycle Setting Register	LPTPRD	16	16	3 ICLK
0008 00B8h	LPT	Low-Power Timer Compare Register 0	LPCMR0	16	16	3 ICLK
0008 00BCh	LPT	Low-Power Timer Standby Wakeup Enable Register	LPWUCR	16	16	3 ICLK
0008 00C0h	SYSTEM	Reset Status Register 2	RSTSR2	8	8	3 ICLK
0008 00C2h	SYSTEM	Software Reset Register	SWRR	16	16	3 ICLK
0008 00E0h	SYSTEM	Voltage Monitoring 1 Circuit Control Register 1	LVD1CR1	8	8	3 ICLK
0008 00E1h	SYSTEM	Voltage Monitoring 1 Circuit Status Register	LVD1SR	8	8	3 ICLK
0008 00E2h	SYSTEM	Voltage Monitoring 2 Circuit Control Register 1	LVD2CR1	8	8	3 ICLK
0008 00E3h	SYSTEM	Voltage Monitoring 2 Circuit Status Register	LVD2SR	8	8	3 ICLK
0008 03FEh	SYSTEM	Protect Register	PRCR	16	16	3 ICLK
0008 1300h	BSC	Bus Error Status Clear Register	BERCLR	8	8	2 ICLK
0008 1304h	BSC	Bus Error Monitoring Enable Register	BEREN	8	8	2 ICLK
0008 1308h	BSC	Bus Error Status Register 1	BERSR1	8	8	2 ICLK
0008 130Ah	BSC	Bus Error Status Register 2	BERSR2	16	16	2 ICLK
0008 1310h	BSC	Bus Priority Control Register	BUSPRI	16	16	2 ICLK
0008 2400h	DTC	DTC Control Register	DTCCR	8	8	2 ICLK
0008 2404h	DTC	DTC Vector Base Register	DTCVBR	32	32	2 ICLK
0008 2408h	DTC	DTC Address Mode Register	DTCADMOD	8	8	2 ICLK

Table 4.1 List of I/O Registers (Address Order) (17 / 18)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles
000A 0B05h	REMC0	Compare Value Setting Register	REMCPD	8	8	1 or 2 PCLKB
000A 0B06h	REMC0	Header Pattern Minimum Width Setting Register	HDPMIN	16	16	1 or 2 PCLKB
000A 0B08h	REMC0	Header Pattern Maximum Width Setting Register	HDPMAX	16	16	1 or 2 PCLKB
000A 0B0Ah	REMC0	Data '0' Pattern Minimum Width Setting Register	D0PMIN	8	8	1 or 2 PCLKB
000A 0B0Bh	REMC0	Data '0' Pattern Maximum Width Setting Register	D0PMAX	8	8	1 or 2 PCLKB
000A 0B0Ch	REMC0	Data '1' Pattern Minimum Width Setting Register	D1PMIN	8	8	1 or 2 PCLKB
000A 0B0Dh	REMC0	Data '1' Pattern Maximum Width Setting Register	D1PMAX	8	8	1 or 2 PCLKB
000A 0B0Eh	REMC0	Special Data Pattern Minimum Width Setting Register	SDPMIN	16	16	1 or 2 PCLKB
000A 0B10h	REMC0	Special Data Pattern Maximum Width Setting Register	SDPMAX	16	16	1 or 2 PCLKB
000A 0B12h	REMC0	Pattern End Setting Register	REMPE	16	16	1 or 2 PCLKB
000A 0B14h	REMC0	Reception Standby Control Register	REMSTC	8	8	1 or 2 PCLKB
000A 0B15h	REMC0	Receive Bit Count Register	REMRBIT	8	8	1 or 2 PCLKB
000A 0B16h	REMC0	Receive Data 0 Register	REMDAT0	8	8	1 or 2 PCLKB
000A 0B17h	REMC0	Receive Data 1 Register	REMDAT1	8	8	1 or 2 PCLKB
000A 0B18h	REMC0	Receive Data 2 Register	REMDAT2	8	8	1 or 2 PCLKB
000A 0B19h	REMC0	Receive Data 3 Register	REMDAT3	8	8	1 or 2 PCLKB
000A 0B1Ah	REMC0	Receive Data 4 Register	REMDAT4	8	8	1 or 2 PCLKB
000A 0B1Bh	REMC0	Receive Data 5 Register	REMDAT5	8	8	1 or 2 PCLKB
000A 0B1Ch	REMC0	Receive Data 6 Register	REMDAT6	8	8	1 or 2 PCLKB
000A 0B1Dh	REMC0	Receive Data 7 Register	REMDAT7	8	8	1 or 2 PCLKB
000A 0B1Eh	REMC0	Measurement Result Register	REMTIM	16	16	1 or 2 PCLKB
000A 0B80h	REMC1	Function Select Register 0	REMCON0	8	8	1 or 2 PCLKB
000A 0B81h	REMC1	Function Select Register 1	REMCON1	8	8	1 or 2 PCLKB
000A 0B82h	REMC1	Status Register	REMSTS	8	8	1 or 2 PCLKB
000A 0B83h	REMC1	Interrupt Control Register	REMINT	8	8	1 or 2 PCLKB
000A 0B84h	REMC1	Compare Control Register	REMCPC	8	8	1 or 2 PCLKB
000A 0B85h	REMC1	Compare Value Setting Register	REMCPD	8	8	1 or 2 PCLKB
000A 0B86h	REMC1	Header Pattern Minimum Width Setting Register	HDPMIN	16	16	1 or 2 PCLKB
000A 0B88h	REMC1	Header Pattern Maximum Width Setting Register	HDPMAX	16	16	1 or 2 PCLKB
000A 0B8Ah	REMC1	Data '0' Pattern Minimum Width Setting Register	D0PMIN	8	8	1 or 2 PCLKB
000A 0B8Bh	REMC1	Data '0' Pattern Maximum Width Setting Register	D0PMAX	8	8	1 or 2 PCLKB
000A 0B8Ch	REMC1	Data '1' Pattern Minimum Width Setting Register	D1PMIN	8	8	1 or 2 PCLKB
000A 0B8Dh	REMC1	Data '1' Pattern Maximum Width Setting Register	D1PMAX	8	8	1 or 2 PCLKB
000A 0B8Eh	REMC1	Special Data Pattern Minimum Width Setting Register	SDPMIN	16	16	1 or 2 PCLKB
000A 0B90h	REMC1	Special Data Pattern Maximum Width Setting Register	SDPMAX	16	16	1 or 2 PCLKB
000A 0B92h	REMC1	Pattern End Setting Register	REMPE	16	16	1 or 2 PCLKB
000A 0B94h	REMC1	Reception Standby Control Register	REMSTC	8	8	1 or 2 PCLKB
000A 0B95h	REMC1	Receive Bit Count Register	REMRBIT	8	8	1 or 2 PCLKB
000A 0B96h	REMC1	Receive Data 0 Register	REMDAT0	8	8	1 or 2 PCLKB
000A 0B97h	REMC1	Receive Data 1 Register	REMDAT1	8	8	1 or 2 PCLKB
000A 0B98h	REMC1	Receive Data 2 Register	REMDAT2	8	8	1 or 2 PCLKB
000A 0B99h	REMC1	Receive Data 3 Register	REMDAT3	8	8	1 or 2 PCLKB
000A 0B9Ah	REMC1	Receive Data 4 Register	REMDAT4	8	8	1 or 2 PCLKB
000A 0B9Bh	REMC1	Receive Data 5 Register	REMDAT5	8	8	1 or 2 PCLKB
000A 0B9Ch	REMC1	Receive Data 6 Register	REMDAT6	8	8	1 or 2 PCLKB
000A 0B9Dh	REMC1	Receive Data 7 Register	REMDAT7	8	8	1 or 2 PCLKB
000A 0B9Eh	REMC1	Measurement Result Register	REMTIM	16	16	1 or 2 PCLKB
000A 0C00h	REMCOM	HOCO Clock Supply Control Register	HOSCR	8	8	1 or 2 PCLKB
007F C090h	FLASH	E2 DataFlash Control Register	DFLCTL	8	8	2 or 3 FCLK
007F C0ACh	TEMPS	Temperature Sensor Calibration Data Register	TSCDRL	8	8	2 or 3 FCLK
007F C0ADh	TEMPS	Temperature Sensor Calibration Data Register	TSCDRH	8	8	2 or 3 FCLK
007F C0B0h	FLASH	Flash Start-Up Setting Monitor Register	FSCMR	16	16	2 or 3 FCLK

5. Electrical Characteristics

5.1 Absolute Maximum Ratings

Table 5.1 Absolute Maximum Ratings

Conditions: VSS = AVSS0 = VREFL0 = 0 V

Item		Symbol	Value	Unit
Power supply voltage		VCC	–0.3 to +6.5	V
Input voltage	Ports for 5 V tolerant*1	V_{in}	–0.3 to +6.5	V
	Ports P03 to P07, Ports P40 to P47, Ports PJ6, PJ7		–0.3 to AVCC0 + 0.3	V
	Ports other than above		–0.3 to VCC + 0.3	
Reference power supply voltage		VREFH0	–0.3 to AVCC0 + 0.3	V
Analog power supply voltage		AVCC0	–0.3 to +6.5	V
Analog input voltage	When AN000 to AN007 used	V_{AN}	–0.3 to AVCC0 + 0.3	V
	When AN016 to AN031 used		–0.3 to VCC + 0.3	
Operating temperature*2		T_{opr}	–40 to +85 –40 to +105	°C
Storage temperature		T_{stg}	–55 to +125	°C

Caution: Permanent damage to the MCU may result if absolute maximum ratings are exceeded.

To preclude any malfunctions due to noise interference, insert capacitors of high frequency characteristics between the VCC and VSS pins, between the AVCC0 and AVSS0 pins, and between the VREFH0 and VREFL0 pins. Place capacitors of about 0.1 µF as close as possible to every power supply pin and use the shortest and heaviest possible traces.

Connect the VCL pin to a VSS pin via a 4.7 µF capacitor. The capacitor must be placed close to the pin, refer to section 5.13.1, Connecting VCL Capacitor and Bypass Capacitors

Do not input signals or an I/O pull-up power supply to ports other than 5-V tolerant ports while the device is not powered.

The current injection that results from input of such a signal or I/O pull-up may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements.

Even if –0.3 to +6.5 V is input to 5-V tolerant ports, it will not cause problems such as damage to the MCU.

Note 1. Ports P12, P13, P16, and P17 are 5 V tolerant.

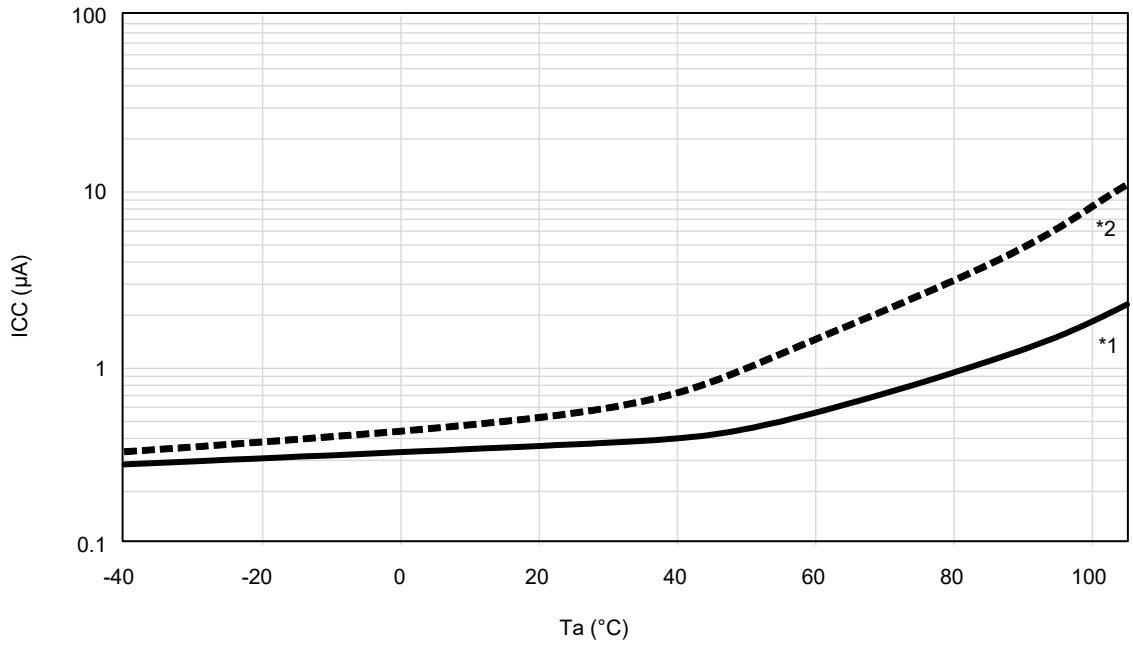
Note 2. The upper limit of operating temperature is 85°C or 105°C, depending on the product. For details, refer to section 1.2, List of Products.

[Products with at least 256 Kbytes of flash memory or 100-pin packages]

Table 5.8 DC Characteristics (5)

Conditions: 1.8 V ≤ VCC = AVCC0 < 2.0 V, 2.0 V ≤ VCC ≤ 5.5 V, 2.0 V ≤ AVCC0 ≤ 5.5 V, VSS = AVSS0 = 0 V, Ta = –40 to +105°C

Item					Symbol	Typ.	Max.	Unit	Test Conditions
Supply current*1	High-speed operating mode	Normal operating mode	No peripheral operation*2	ICLK = 32MHz	I_{CC}	3.5	—	mA	
				ICLK = 16MHz		2.4	—		
				ICLK = 8MHz		1.8	—		
			All peripheral operation: Normal*3	ICLK = 32MHz		12.4	—		
				ICLK = 16MHz		7.0	—		
				ICLK = 8MHz		4.3	—		
			All peripheral operation: Max.*3	ICLK = 32MHz		—	25.4		
		Sleep mode	No peripheral operation*2	ICLK = 32MHz		1.8	—		
				ICLK = 16MHz		1.4	—		
				ICLK = 8MHz		1.2	—		
			All peripheral operation: Normal*3	ICLK = 32MHz		6.5	—		
				ICLK = 16MHz		3.8	—		
				ICLK = 8MHz		2.5	—		
		Deep sleep mode	No peripheral operation*2	ICLK = 32MHz		1.1	—		
				ICLK = 16MHz		0.9	—		
				ICLK = 8MHz		0.8	—		
			All peripheral operation: Normal*3	ICLK = 32MHz		5.2	—		
				ICLK = 16MHz		3.0	—		
				ICLK = 8MHz		1.9	—		
		Increase during flash rewrite*5				2.5	—		
	Middle-speed operating modes	Normal operating mode	No peripheral operation*6	ICLK = 12MHz	I_{CC}	2.1	—	mA	
				ICLK = 8MHz		1.4	—		
				ICLK = 4MHz		0.7	—		
				ICLK = 1MHz		0.3	—		
			All peripheral operation: Normal*7	ICLK = 12MHz		5.5	—		
				ICLK = 8MHz		3.9	—		
				ICLK = 4MHz		2.4	—		
				ICLK = 1MHz		1.1	—		
			All peripheral operation: Max.*7	ICLK = 12MHz		—	11.6		
		Sleep mode	No peripheral operation*6	ICLK = 12MHz	I_{CC}	1.4	—	mA	
				ICLK = 8MHz		0.8	—		
				ICLK = 4MHz		0.3	—		
				ICLK = 1MHz		0.2	—		
			All peripheral operation: Normal*7	ICLK = 12MHz		3.2	—		
				ICLK = 8MHz		2.2	—		
				ICLK = 4MHz		1.4	—		
				ICLK = 1MHz		0.8	—		



Note 1. Average value of the tested middle samples during product evaluation.
Note 2. Average value of the tested upper-limit samples during product evaluation.

Figure 5.8 Temperature Dependency in Software Standby Mode (Reference Data)

Table 5.17 Permissible Output Currents (1)

Conditions: 1.8 V ≤ VCC = AVCC0 < 2.0 V, 2.0 V ≤ VCC ≤ 5.5 V, 2.0 V ≤ AVCC0 ≤ 5.5 V, VSS = AVSS0 = 0 V, Ta = –40 to +85°C

Item			Symbol	Max.	Unit
Permissible output low current (average value per pin)	Ports P03 to P07, Ports P40 to P47, Ports PJ6, PJ7		I_{OL}	4.0	mA
	Ports other than above	Normal output mode		4.0	
		High-drive output mode		8.0	
Permissible output low current (maximum value per pin)	Ports P03 to P07, Ports P40 to P47, Ports PJ6, PJ7			4.0	
	Ports other than above	Normal output mode		4.0	
		High-drive output mode		8.0	
Permissible output low current	Total of Ports P03 to P07, Ports P40 to P47, Ports PJ6, PJ7		ΣI_{OL}	40	
	Total of Ports P12 to P17, Ports P20 to P27, Ports P30 to P37, Ports PH2, PH3, Ports PJ1, PJ3			40	
	Total of Ports P50 to P55, Ports PB0 to PB7, Ports PC0 to PC7, Ports PH0, PH1			40	
	Total of Ports PA0 to PA7, Ports PD0 to PD7, Ports PE0 to PE7			40	
	Total of all output pins			80	
Permissible output high current (average value per pin)	Ports P03 to P07, Ports P40 to P47, Ports PJ6, PJ7		I_{OH}	–4.0	
	Ports other than above	Normal output mode		–4.0	
		High-drive output mode		–8.0	
Permissible output high current (maximum value per pin)	Ports P03 to P07, Ports P40 to P47, Ports PJ6, PJ7			–4.0	
	Ports other than above	Normal output mode		–4.0	
		High-drive output mode		–8.0	
Permissible output high current	Total of Ports P03 to P07, Ports P40 to P47, Ports PJ6, PJ7		ΣI_{OH}	–40	
	Total of Ports P12 to P17, Ports P20 to P27, Ports P30 to P37, Ports PH2, PH3, Ports PJ1, PJ3			–40	
	Total of Ports P50 to P55, Ports PB0 to PB7, Ports PC0 to PC7, Ports PH0, PH1			–40	
	Total of Ports PA0 to PA7, Ports PD0 to PD7, Ports PE0 to PE7			–40	
	Total of all output pins			–80	

Note: Do not exceed the permissible total supply current.

5.2.3 Normal I/O Pin Output Characteristics (3)

Figure 5.22 to Figure 5.25 show the characteristics of the RIIC output pin.

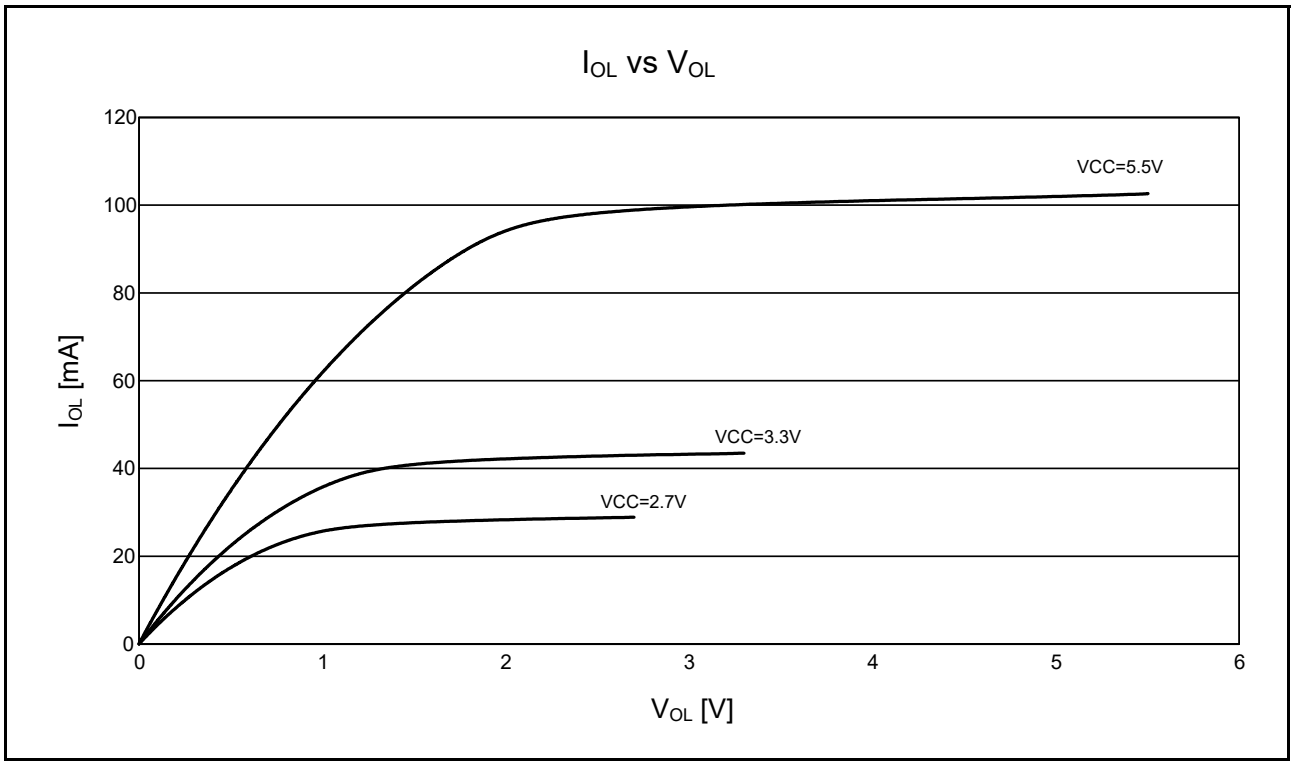


Figure 5.22 V_{OL} and I_{OL} Voltage Characteristics of RIIC Output Pin at T_a = 25°C (Reference Data)

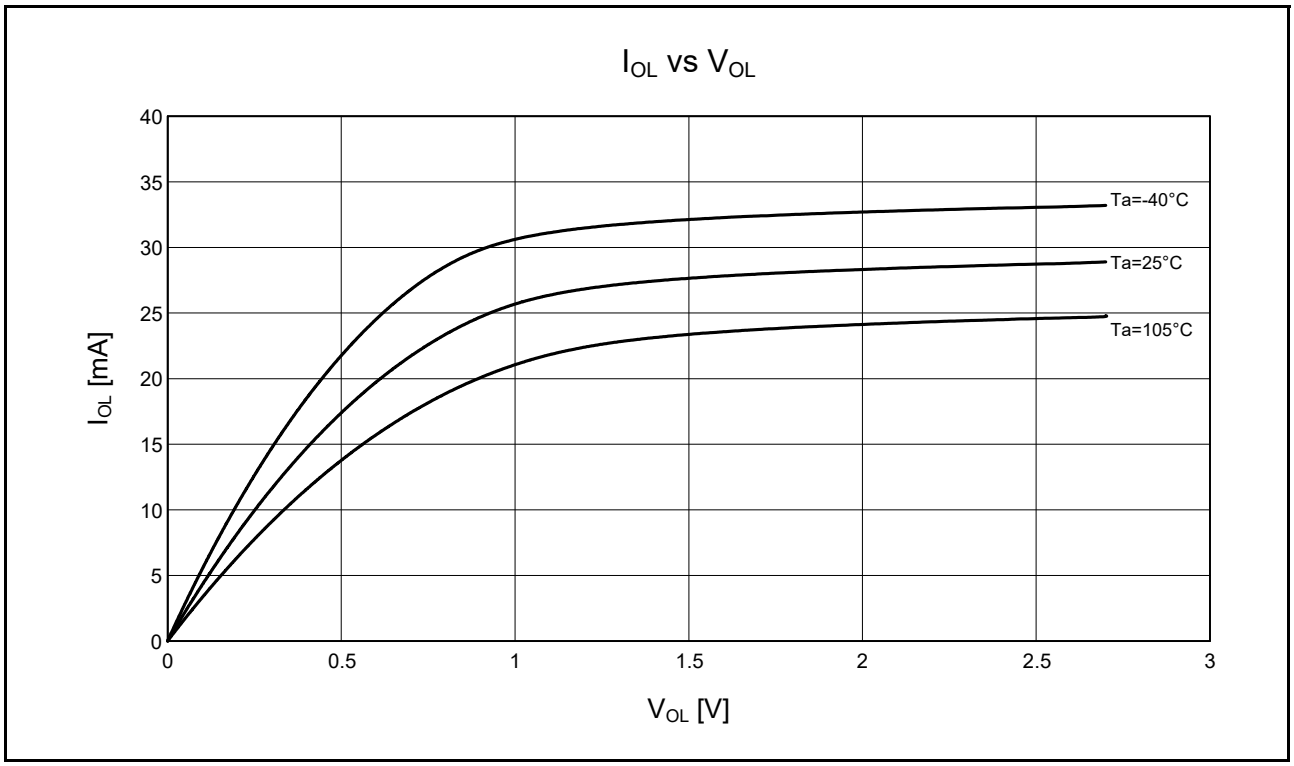


Figure 5.23 V_{OL} and I_{OL} Temperature Characteristics of RIIC Output Pin at VCC = 2.7 V (Reference Data)

When the main clock oscillator wait control register (MOSCWTCR) is set to 00h.

Table 5.29 Timing of Recovery from Low Power Consumption Modes (3)

Conditions: 1.8 V ≤ VCC = AVCC0 < 2.0 V, 2.0 V ≤ VCC ≤ 5.5 V, 2.0 V ≤ AVCC0 ≤ 5.5 V, VSS = AVSS0 = 0 V, Ta = –40 to +105°C

Item			Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	Low-speed mode	Sub-clock oscillator operating	t_{SBYSC}	—	600	750	µs	Figure 5.37

Note: Note Values when the frequencies of PCLKB, PCLKD, and FCLK are not divided.
Note 1. The sub-clock continues oscillating in software standby mode during low-speed mode.

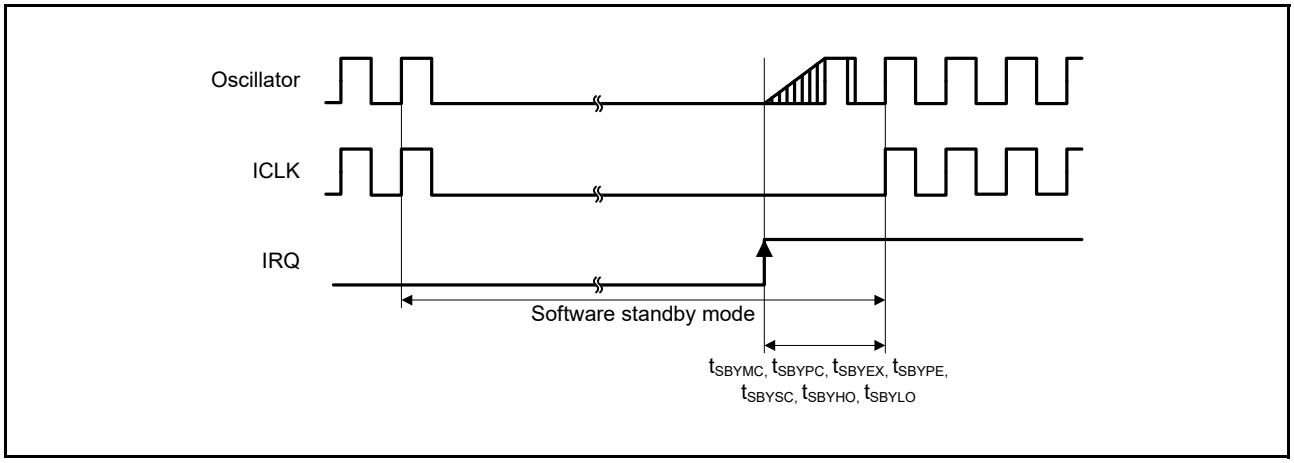


Figure 5.37 Software Standby Mode Recovery Timing

Table 5.30 Timing of Recovery from Low Power Consumption Modes (4)

Conditions: 1.8 V ≤ VCC = AVCC0 < 2.0 V, 2.0 V ≤ VCC ≤ 5.5 V, 2.0 V ≤ AVCC0 ≤ 5.5 V, VSS = AVSS0 = 0 V, Ta = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from deep sleep mode*1	High-speed mode*2	t_{DSLP}	—	2	3.5	µs	Figure 5.38
	Middle-speed mode*3	t_{DSLP}	—	3	4	µs	
	Low-speed mode*4	t_{DSLP}	—	400	500	µs	

Note: Note Values when the frequencies of PCLKB, PCLKD, and FCLK are not divided.
Note 1. Oscillators continue oscillating in deep sleep mode.
Note 2. When the frequency of the system clock is 32 MHz.
Note 3. When the frequency of the system clock is 12 MHz.
Note 4. When the frequency of the system clock is 32.768 kHz.

Table 5.33 Timing of On-Chip Peripheral Modules (1)

Conditions: 1.8 V ≤ VCC = AVCC0 < 2.0 V, 2.0 V ≤ VCC ≤ 5.5 V, 2.0 V ≤ AVCC0 ≤ 5.5 V, VSS = AVSS0 = 0 V, Ta = –40 to +105°C

Item			Symbol	Min.	Max.	Unit *1	Test Conditions
CLKOUT	CLKOUT pin output cycle*4	VCC = 2.7 V or above	t_{Ccyc}	62.5	—	ns	Figure 5.49
		VCC = 1.8 V or above		125			
	CLKOUT pin high pulse width*3	VCC = 2.7 V or above	t_{CH}	15	—	ns	
		VCC = 1.8 V or above		30			
	CLKOUT pin low pulse width*3	VCC = 2.7 V or above	t_{CL}	15	—	ns	
		VCC = 1.8 V or above		30			
	CLKOUT pin output rise time	VCC = 2.7 V or above	t_{Cr}	—	12	ns	
		VCC = 1.8 V or above			25		
	CLKOUT pin output fall time	VCC = 2.7 V or above	t_{Cf}	—	12	ns	
		VCC = 1.8 V or above			25		

Note 1. t_{Pcyc}: PCLK cycle
Note 2. t_{cac}: CAC count clock source cycle
Note 3. When the LOCO is selected as the clock output source (CKOCR.CKOSEL[3:0] bits = 0000b), set the clock output division ratio selection to divided by 2 (CKOCR.CKODIV[2:0] bits = 001b).
Note 4. When the XTAL external clock input or an oscillator is used with divided by 1 (CKOCR.CKOSEL[3:0] bits = 010b and CKOCR.CKODIV[2:0] bits = 000b) to output from CLKOUT, the above should be satisfied with an input duty cycle of 45 to 55%.

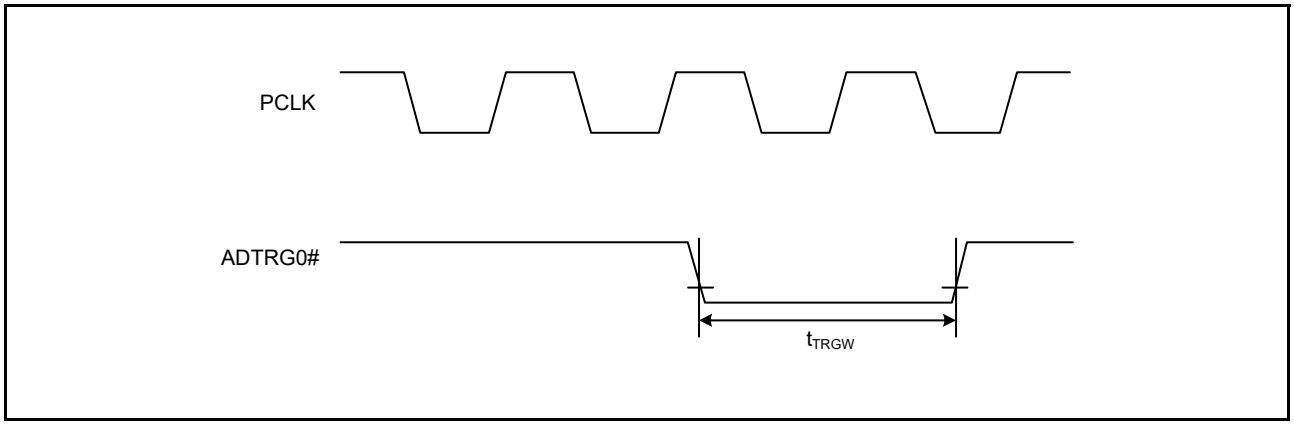


Figure 5.48 A/D Converter External Trigger Input Timing

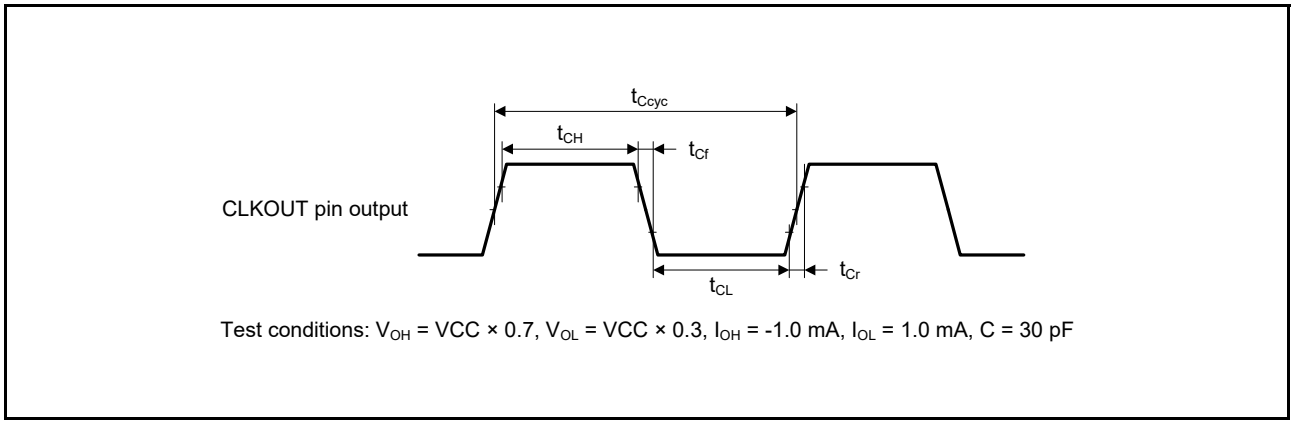


Figure 5.49 CLKOUT Output Timing

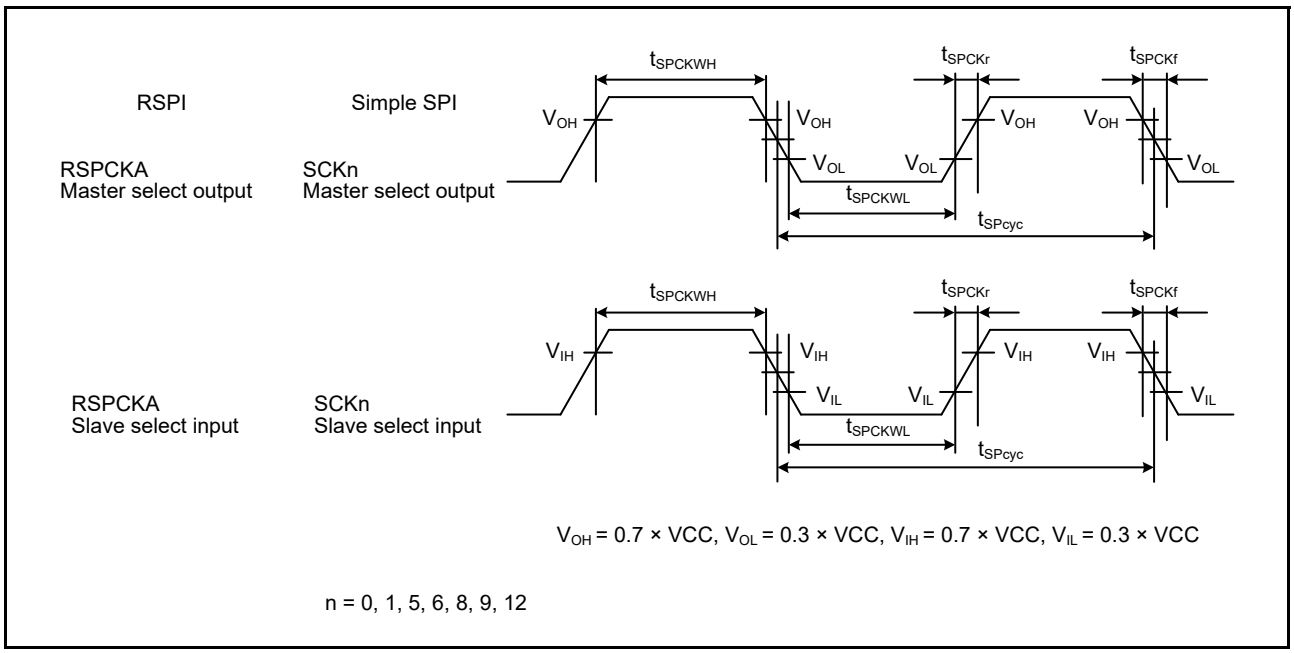


Figure 5.50 RSPI Clock Timing and Simple SPI Clock Timing

Table 5.43 A/D Conversion Characteristics (5)

Conditions: 1.8 V ≤ VCC = AVCC0 < 2.0 V, 2.0 V ≤ VCC ≤ 5.5 V, 2.0 V ≤ AVCC0 ≤ 5.5 V, 1.8 V ≤ VREFH0 ≤ AVCC0,
Reference voltage = VREFH0, VSS = AVSS0 = VREFL0 = 0 V, Ta = –40 to +105°C

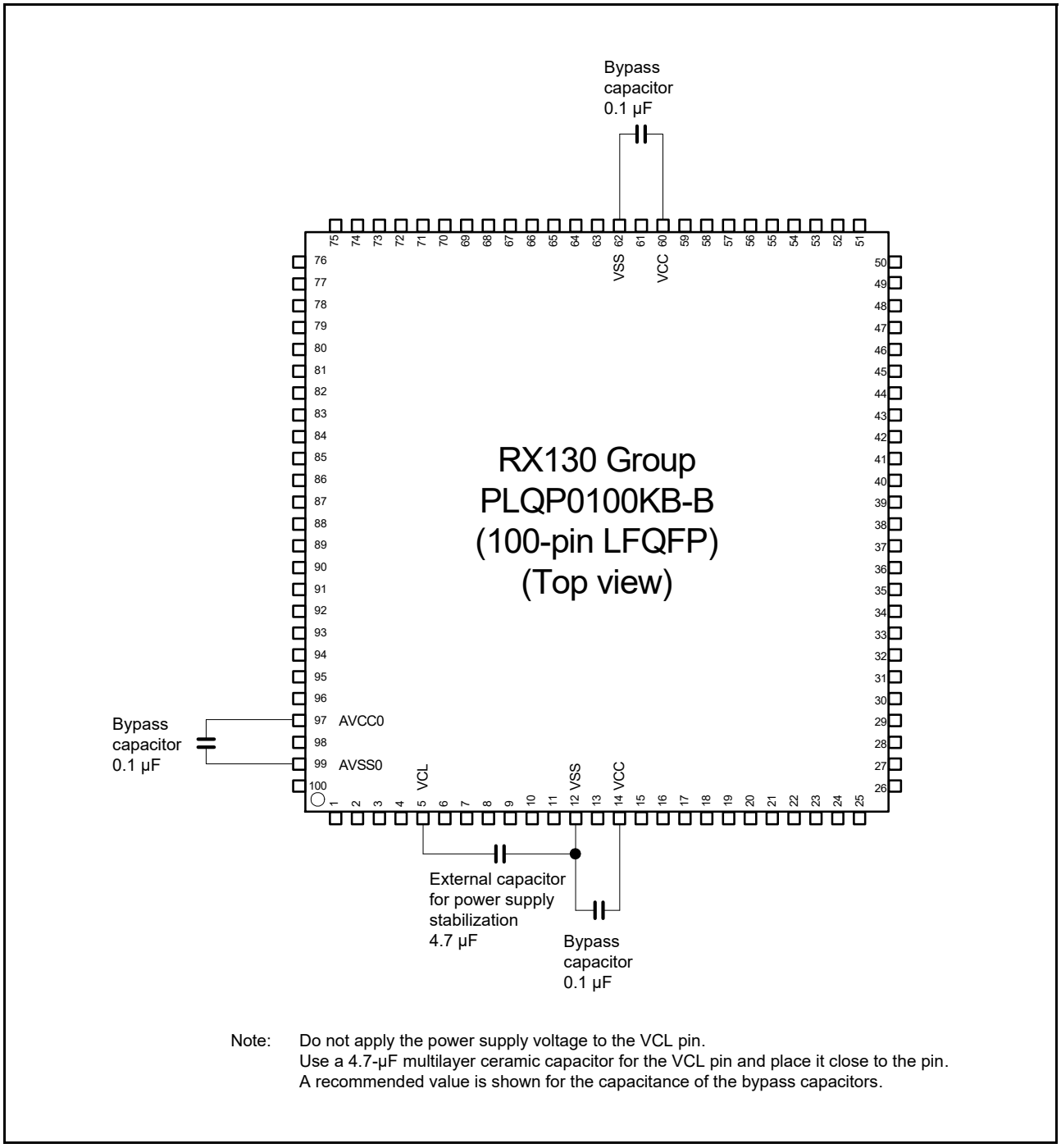
Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		1	—	8	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 8 MHz)	Permissible signal source impedance (Max.) = 5 kΩ	6.75	—	—	µs	High-precision channel ADCSR.ADHSC bit = 1 ADSSTRn = 0Dh
		10.13	—	—		Normal-precision channel ADCSR.ADHSC bit = 1 ADSSTRn = 28h
Analog input capacitance	Cs	—	—	15	pF	Pin capacitance included
Analog input resistance	Rs	—	—	2.5	kΩ	
Analog input effective range		0	—	VREFH0	V	
Offset error		—	±1.0	±7.5	LSB	
Full-scale error		—	±1.5	±7.5	LSB	
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±3.0	±8.0	LSB	
DNL differential nonlinearity error		—	±1.0	—	LSB	
INL integral nonlinearity error		—	±1.25	±3.0	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential nonlinearity error, and INL integral nonlinearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

Table 5.44 A/D Converter Channel Classification

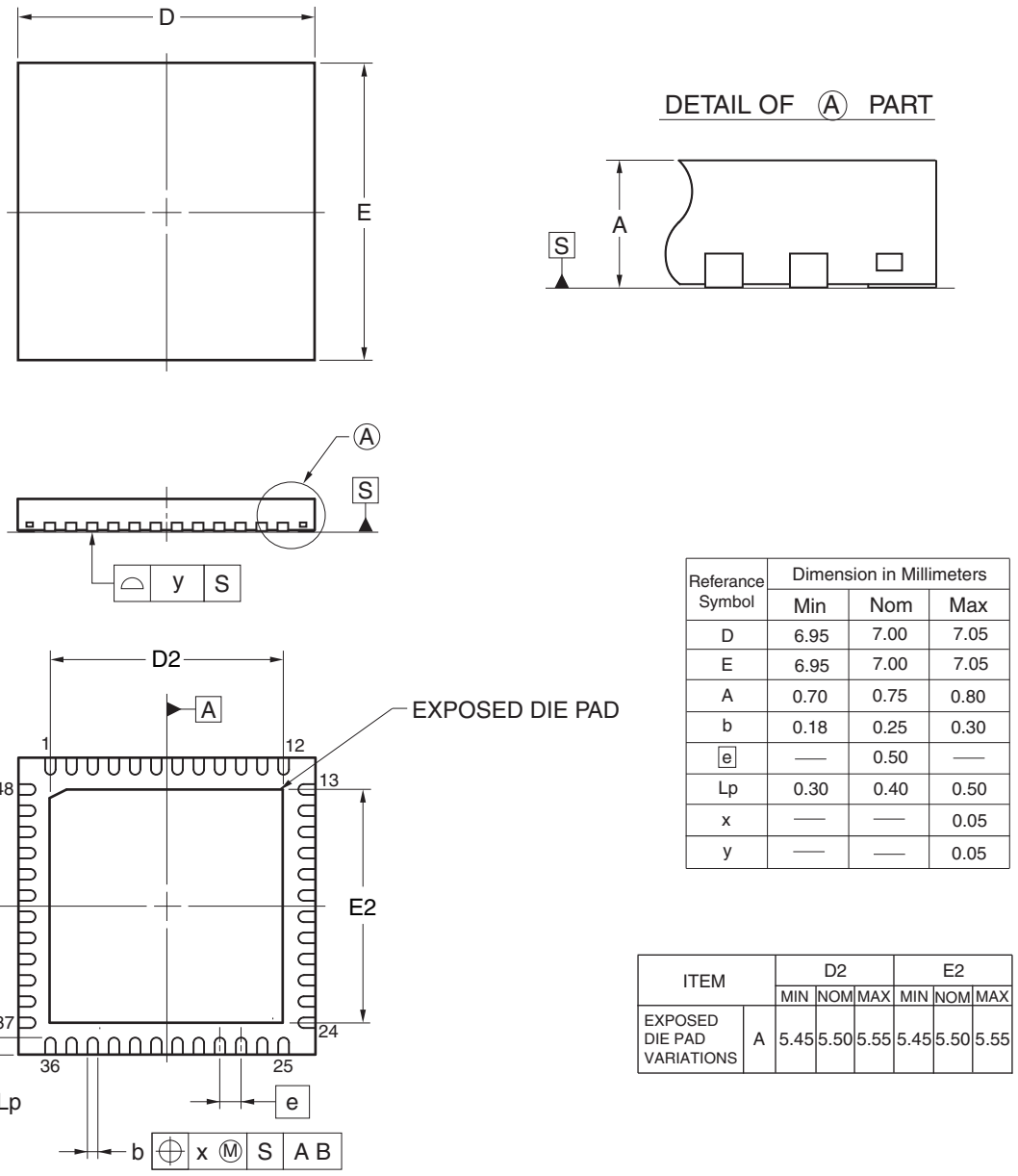
Classification	Channel	Conditions	Remarks
High-precision channel	AN000 to AN007	AVCC0 = 1.8 to 5.5 V	Pins AN000 to AN007 cannot be used as digital outputs when the A/D converter is in use.
Normal-precision channel	AN016 to AN031		
Internal reference voltage input channel	Internal reference voltage	AVCC0 = 2.0 to 5.5 V	
Temperature sensor input channel	Temperature sensor output	AVCC0 = 2.0 to 5.5 V	



Note: Do not apply the power supply voltage to the VCL pin.
Use a 4.7-µF multilayer ceramic capacitor for the VCL pin and place it close to the pin.
A recommended value is shown for the capacitance of the bypass capacitors.

Figure 5.67 Connecting Capacitors (100 Pins)

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-HWQFN48-7x7-0.50	PWQN0048KB-A	48PJN-A P48K8-50-5B4-5	0.13



Referance Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.95	7.00	7.05
E	6.95	7.00	7.05
A	0.70	0.75	0.80
b	0.18	0.25	0.30
e	—	0.50	—
Lp	0.30	0.40	0.50
x	—	—	0.05
y	—	—	0.05

ITEM		D2			E2		
		MIN	NOM	MAX	MIN	NOM	MAX
EXPOSED DIE PAD VARIATIONS	A	5.45	5.50	5.55	5.45	5.50	5.55

Figure E 48-Pin HWQFN (PWQN0048KB-A)

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   ¾ The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   ¾ The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.
   In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   ¾ The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   ¾ When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   ¾ The characteristics of Microprocessing unit or Microcontroller unit products in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.